

	<h1>Tentative</h1>	DB24404	
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DB24404

Silicon epitaxial planar type

For rectification

Marking Symbol : A8

Package Code : TMiniP2-F2-B

Absolute Maximum Ratings $T_a = 25\text{ }^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	VR	40	V
Maximum peak reverse voltage	VRM	40	V
Forward current (Average) *1	IF (AV)	3.0	A
Non-repetitive peak forward surge current	IFSM	60	A
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-40 to +125	°C

Pin name	1.	Cathode
	2.	Anode

Note: 1. *1 50Hz sine wave 1 cycle (Non-repetitive peak current)

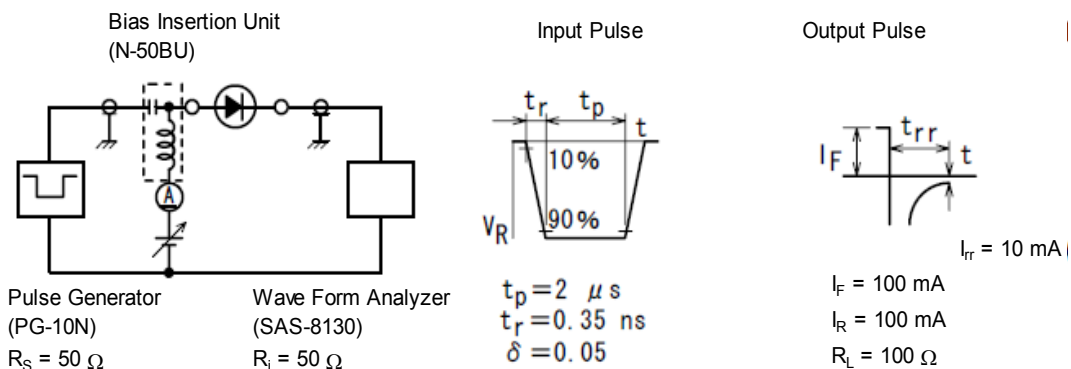
Electrical Characteristics $T_a = 25\text{ }^\circ\text{C} \pm 3\text{ }^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	VF	IF = 3.0 A			0.53	V
Reverse current	IR	VR = 40 V			50	μA
Terminal capacitance	Ct	VR = 10 V, f = 1 MHz		85		pF
Reverse recovery time *1	trr	IF = IR = 100 mA Irr = 10 mA, RL = 100 Ω		30		ns

Note: 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. *1 trr Test Circuit



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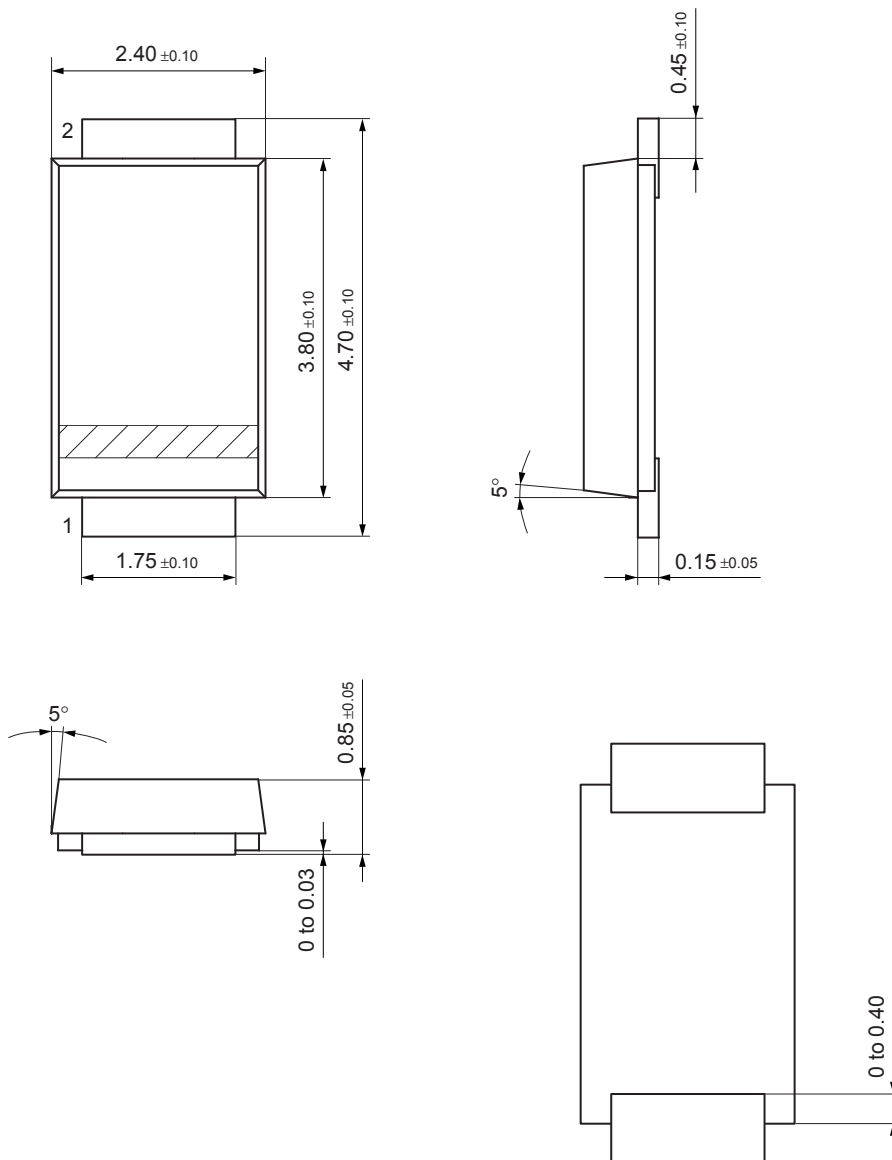
Packing

Embossed type (Thermo-compression sealing) : 3 000 pcs / reel

2010.4.23	2010.7.27	
Prepared	Revised	

TMiniP2-F2-B

Unit: mm



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